

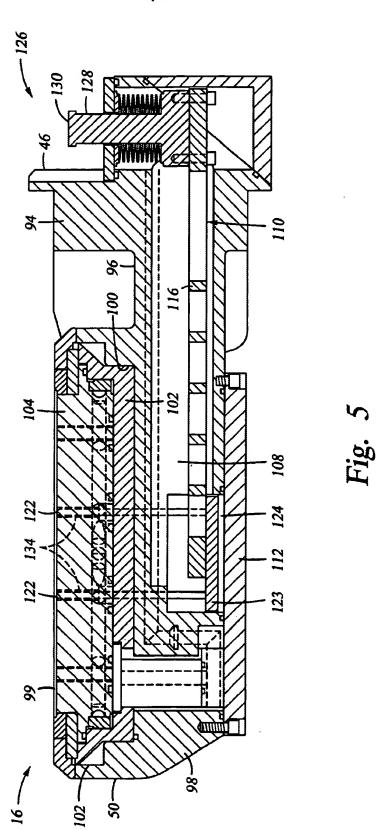


U.S. SERIAL NO.: 09/912,112 CONF. NO.
FILED: JULY 23, 2001
APPLICANT: APPLIED MATERIALS, INC.
TITLE: DOME: SHAPE AND TEMPERATURE CONTROLLED SURFACES
INVENTOR: ISHIKAWA, ET AL.
REPLACEMENT DRAWINGS PAG

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JULY 23, 2001

APPLIED MATERIALS, INC.

DOME: SHAPE AND TEMPERATURE CONTROLLED

SURFACES

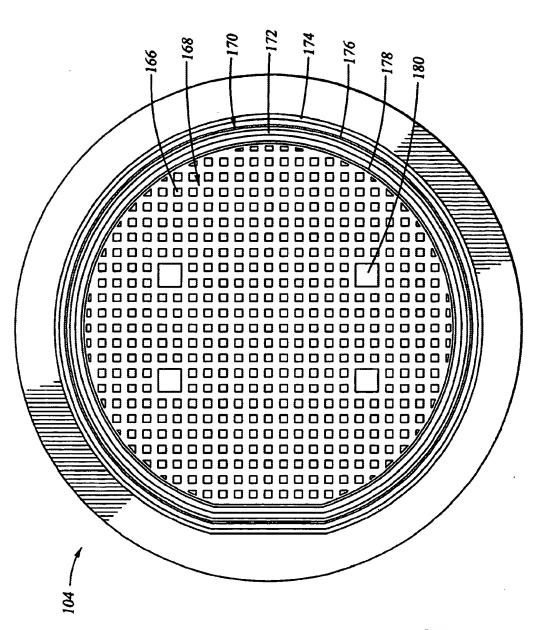
ISHIKAWA, ET AL.

REPLACEMENT DRAWINGS

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TITLE:

ISHIKAWA, ET AL INVENTOR: REPLACEMENT DRAWINGS

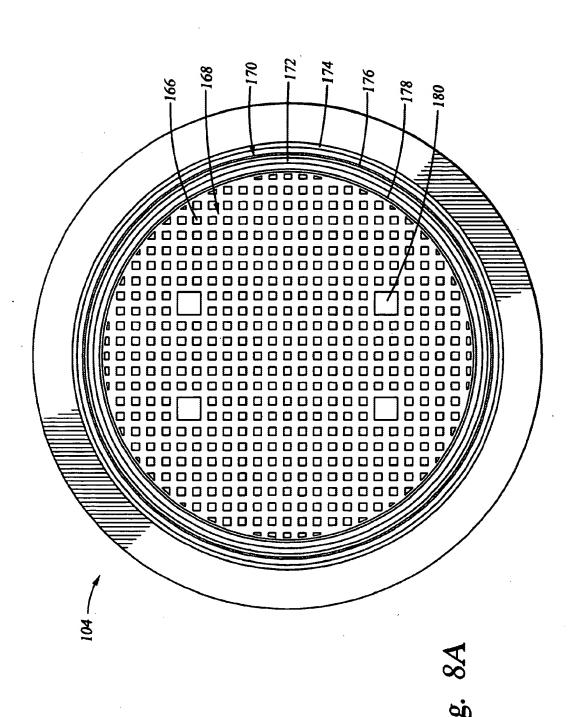
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09/912,112 CONF. N JULY 23, 2001 APPLIED MATERIALS, INC. DOME: SHAPE AND TEMPERATURE CONTROLLED U.S. SERIAL NO.: FILED: CONF. No.: 4580 APPLICANT: TITLE: SURFACES ISHIKAWA, ET AL. INVENTOR: REPLACEMENT DRAWINGS PAGE 9 of 16 ٦ 9/16 TWAFER -210 211 166 166 166 172 182 -208 THERMAL MASS -212 WAFER TEMPERATURE TO ELECTRICAL SIGNAL TRANSFER FUNCTION **HEAT FROM** (TEMPERATURE SENSOR) **PLASMA** - 192 991 991 -202 (HEATER/COOLING SYSTEM) **HEAT TRANSFER** 991 991 99 TO / FROM ESC 196 184 991 991 991 -200 CONTROLLER) -214 HELIUM HEAT TRANSFER FUNCTION **FEED BACK** (PRESSURE **TRANSFER FUNCTION** 172 -113 -186 190 **TSETPOINT**

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